



Material Content Data Sheet



Sales Product Name				BGSX 22G5A10 E6327		Issued		12. February 2019	
MA#				MA004645456					
Package				PG-ATSLP-10-50		Weight*		2.27 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	0.352	15.50	15.50	155022	155022	
bumps	noble metal	silver	7440-22-4	0.000	0.00		44		
	non noble metal	nickel	7440-02-0	0.001	0.04		446		
	non noble metal	tin	7440-31-5	0.005	0.22		2231		
encapsulation	non noble metal	copper	7440-50-8	0.014	0.62	0.88	6202	8923	
	organic material	carbon black	1333-86-4	0.002	0.10		982		
	plastics	epoxy resin	-	0.132	5.79		57933		
leadfinish	inorganic material	silicondioxide	60676-86-0	0.982	43.19	49.08	432042	490957	
	noble metal	palladium	7440-05-3	0.000	0.02		162		
	noble metal	gold	7440-57-5	0.001	0.03		261		
substrate	non noble metal	nickel	7440-02-0	0.011	0.48	0.53	4762	5185	
	organic material	carbon black	1333-86-4	0.000	0.02		162		
	plastics	epoxy resin	-	0.031	1.38		13835		
solder	inorganic material	silicondioxide	60676-86-0	0.213	9.37		93670		
	non noble metal	copper	7440-50-8	0.520	22.90	33.67	228958	336625	
	noble metal	silver	7440-22-4	0.000	0.01		74		
ubm	non noble metal	tin	7440-31-5	0.007	0.32	0.33	3151	3225	
	non noble metal	titanium	7440-32-6	0.000	0.00		7		
*deviation	non noble metal	copper	7440-50-8	0.000	0.01	0.01	56	63	
						Sum in total:		100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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